

Docket No. 55413 (71987)

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: P. Yuan et al.

U.S.S.N.: 09/718,669

GROUP: 2814

FILED: November 22, 2000

EXAMINER: D. Nguyen

FOR: TAPE CARRIER PACKAGE STRUCTURE WITH DUMMY PADS  
AND DUMMY LEADS FOR PACKAGE REINFORCEMENT

## CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to Group 2800 of the U.S. Patent & Trademark Office by facsimile number 703-872-9319 on August 1, 2002.

By:   
Steven M. Jensen

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

**EXAMINING GROUP 2814  
AMENDMENT AFTER FINAL  
UNDER 37 C.F.R. 116 EXPEDITED PROCEDURE**

Applicants are in receipt of the Office Action dated April 17, 2002 of the above-referenced application. A request for a one-month extension of time is submitted herewith. Please amend the application as follows:

## IN THE CLAIMS

Please amend claims 1, 6, and 10 as follows:

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1. (Amended) A tape carrier package structure, which comprises:
    - (a) a semiconductor chip having:
      - (a1) a plurality of I/O pads arranged along the sides thereof; and
      - (a2) a plurality of dummy pads arranged on the corners thereof;